

PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr> <td>Deog-Kyoon Jeong</td> <td>05/11/2009</td> </tr> <tr> <td>Suhwan Kim</td> <td>05/11/2009</td> </tr> <tr> <td>Woo-Yeol Shin</td> <td>05/11/2009</td> </tr> <tr> <td>Dong-Hyuk Lim</td> <td>05/11/2009</td> </tr> <tr> <td>Ic-Su Oh</td> <td>05/11/2009</td> </tr> </tbody> </table>		Name	Execution Date	Deog-Kyoon Jeong	05/11/2009	Suhwan Kim	05/11/2009	Woo-Yeol Shin	05/11/2009	Dong-Hyuk Lim	05/11/2009	Ic-Su Oh	05/11/2009
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<table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 20%;">Name:</td> <td>HYNIX SEMICONDUCTOR INC.</td> </tr> <tr> <td>Street Address:</td> <td>San 136-1, Ami-ri, Bubal-eup</td> </tr> <tr> <td>City:</td> <td>Icheon-si, Gyeonggi-do</td> </tr> <tr> <td>State/Country:</td> <td>REPUBLIC OF KOREA</td> </tr> </table>		Name:	HYNIX SEMICONDUCTOR INC.	Street Address:	San 136-1, Ami-ri, Bubal-eup	City:	Icheon-si, Gyeonggi-do	State/Country:	REPUBLIC OF KOREA				
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PROPERTY NUMBERS Total: 1													
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CORRESPONDENCE DATA													
<p>Fax Number: (703)865-5150 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 703-652-3820 Email: JBAK@MANNAVAKANG.COM</p> <p>Correspondent Name: Jung Kim Address Line 1: 11240 WAPLES MILL ROAD Address Line 2: Suite 300 Address Line 4: FAIRFAX, VIRGINIA 22030</p>													
ATTORNEY DOCKET NUMBER:	P09H0099/US												
NAME OF SUBMITTER:	Jung H. Kim												

OP \$40.00 12477545

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PATENT
REEL: 022775 FRAME: 0200

Total Attachments: 4

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ASSIGNMENT OF PATENT APPLICATION

WHEREAS I/We, the below named inventor(s) has made an invention entitled:

BI-DIRECTIONAL MULTI-DROP BUS MEMORY SYSTEM

For which I/We executed an application for Letters Patent of the United States concurrently herewith; and/or
For which I/We filed an application for Letters Patent of the United States on June 3, 2009 (Application
No. 12/477,545),

BE IT KNOWN that, for good and valuable consideration, the receipt of which is hereby acknowledged, I/We, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto **Hynix Semiconductor, Inc. and SEOUL NATIONAL UNIVERSITY INDUSTRY FOUNDATION**, a corporation of the Republic of Korea, whose post office address is **San 136-1, Ami-ri, Bubal-eup, Ichon-si, Gyeonggi-do 467-701, Republic of Korea and San 4-2, Bongcheon 7-dong, Gwanak-gu, Seoul 151-050, Republic of Korea** (hereinafter referred to as Assignee), its lawful successors and assigns my/our entire right, title, and interest in and to this application and the invention(s) and improvement(s) set forth therein; and any and all continuations, continuations-in-part, divisionals, and renewals of and substitutes for said application for said Letters Patent and any and all Letters Patent of the United States and of countries foreign thereto, which may be granted thereon or therefore; and any reissues, reexaminations, or extensions of all such Letters Patent.

I/WE HEREBY authorize the Assignee, its lawful successors and assigns to apply for Letters Patent in all countries foreign to the United States directly in its own name, and to claim priority of the filing date of any of the above-mentioned applications for Letters Patent of the United States and of countries foreign thereto under the provisions of any and all international conventions and treaties.

I/WE HEREBY authorize and request the Commissioner of Patents and Trademarks of the United States and official of any country or countries foreign to the United States, whose duty it is to issue patents on applications as foresaid, to issue all Letters Patent for this invention to the Assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY covenant that I/We have the full right to convey the interest assigned by this Assignment, and I/We have not executed and will not execute any agreement in conflict with this Assignment;

AND, I/WE HEREBY further covenant and agree that I/We will, without further consideration, communicate with said Assignee, its successors and assigns, any facts known to me/us respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid said Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and in countries foreign thereto, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns.

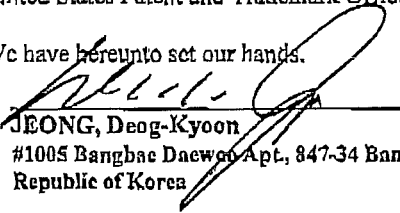
AND, I/WE HEREBY authorize and request the attorneys of record to insert the serial number and filing date of said application now identified by the attorney docket number and title set forth above as soon as the same shall have been known to them by the United States Patent and Trademark Office.

IN TESTIMONY WHEREOF, I/We have hereunto set our hands.

Signature of first assignor:

Name of first assignor:

Address:

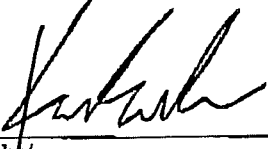

JEONG, Deog-Kyoon

Date

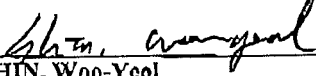
May 11, 2009

#1005 Bangbae Daewon Apt., 847-34 Bangbae 4-dong, Seocho-gu, Seoul 137-836,
Republic of Korea

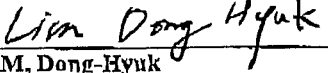
Signature of second assignor:
Name of second assignor:
Address:


Date May 11. 2009
KIM, Suhyun
Seoul National University Faculty House 122C-103, Bongcheon 7-Dong, Kwanak-gu,
Seoul 151-818, Republic of Korea

Signature of third assignor:
Name of third assignor:
Address:


Date May 11. 2009
SHIN, Woo-Yeol
#301 306-26 Haengdang 2-dong, Sungdong-gu, Seoul 133-072, Republic of Korea

Signature of fourth assignor:
Name of fourth assignor:
Address:


Date May 11. 2009
LIM, Dong-Hyuk
#301 ilmsun Villat, 6-11 Garak-dong, Songpa-gu, Seoul 138-800, Republic of Korea

Signature of fifth assignor:
Name of fifth assignor:
Address:

Date _____
OH, Ic-Su
San 136-1, Ami-ri, Bubal-eup, Icheon-si, Gyeonggi-do 467-701, Republic of Korea

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I/WE HEREBY authorize the Assignee, its lawful successors and assigns to apply for Letters Patent in all countries foreign to the United States directly in its own name, and to claim priority of the filing date of any of the above-mentioned applications for Letters Patent of the United States and of countries foreign thereto under the provisions of any and all international conventions and treaties.

I/WE HEREBY authorize and request the Commissioner of Patents and Trademarks of the United States and official of any country or countries foreign to the United States, whose duty it is to issue patents on applications as foreshaid, to issue all Letters Patent for this invention to the Assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY covenant that I/We have the full right to convey the interest assigned by this Assignment, and I/We have not executed and will not execute any agreement in conflict with this Assignment;

AND, I/WE HEREBY further covenant and agree that I/We will, without further consideration, communicate with said Assignee, its successors and assigns, any facts known to me/us respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid said Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and in countries foreign thereto, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys of record to insert the serial number and filing date of said application now identified by the attorney docket number and title set forth above as soon as the same shall have been known to them by the United States Patent and Trademark Office.

IN TESTIMONY WHEREOF, I/We have hereunto set our hands.

Signature of first assignor:
Name of first assignor:
Address:

JEONG, Deog-Kyoon
#1005 Bangbae Daewoo Apt., 847-34 Bangbae 4-dong, Seocho-gu, Seoul 137-836,
Republic of Korea

Date

Signature of second assignor: _____ Date _____
Name of second assignor: **KIM, Suhwan**
Address: **Seoul National University Faculty House 122C-103, Bongcheon 7-Dong, Kwanak-gu,
Seoul 151-818, Republic of Korea**

Signature of third assignor: _____ Date _____
Name of third assignor: **SHIN, Woo-Yeol**
Address: **#301 306-26 Haengdang 2-dong, Sungdong-gu, Seoul 133-072, Republic of Korea**

Signature of fourth assignor: _____ Date _____
Name of fourth assignor: **LIM, Dong-Hyuk**
Address: **#301 ilmsun Villat, 6-11 Garak-dong, Songpa-gu, Seoul 138-800, Republic of Korea**

Signature of fifth assignor: Icsu Oh _____ Date May 11, 2009
Name of fifth assignor: **OH, Ic-Su**
Address: **San 136-1, Ami-ri, Bubal-eup, Icheon-si, Gyeonggi-do 467-701, Republic of Korea**